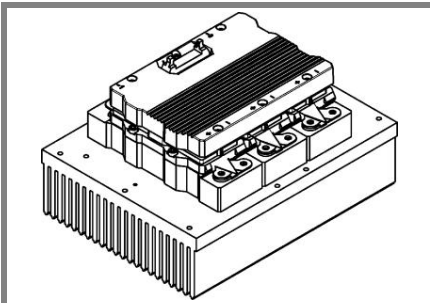


SKiiP 1813GB123-3DL



SKiiP® 3

2-pack-integrated intelligent Power System

Power Section

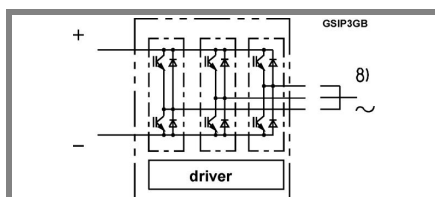
SKiiP 1813GB123-3DL

Data

Power section features

- SKiiP technology inside
- Trench IGBTs
- CAL HD diode technology
- Integrated current sensor
- Integrated temperature sensor
- Integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP® 3 System)
- IEC 60068-1 (climate) 40/125/56
- UL recognized file no. E63532

- 1) with assembly of suitable MKP capacitor per terminal
- 8) AC connection busbars must be connected by the user; copper busbars available on request



Case S33

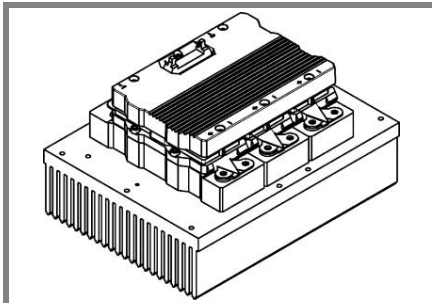
Absolute Maximum Ratings		$T_s = 25\text{ °C}$ unless otherwise specified	
Symbol	Conditions	Values	Units
IGBT			
V_{CES}	Operating DC link voltage	1200	V
$V_{CC}^{1)}$		900	V
V_{GES}		± 20	V
I_C	$T_s = 25\text{ (70) °C}$	1800 (1350)	A
Inverse diode			
$I_F = -I_C$	$T_s = 25\text{ (70) °C}$	1410 (1070)	A
I_{FSM}	$T_j = 150\text{ °C}$, $t_p = 10\text{ ms}$; sin	10200	A
I^2t (Diode)	Diode, $T_j = 150\text{ °C}$, 10 ms	520	kA ² s
T_j , (T_{stg})	rms, AC, 1 min, main terminals to heat sink per AC terminal, rms, $T_s = 70\text{ °C}$, $T_{terminal} < 115\text{ °C}$	- 40 ... + 150 (125)	°C
V_{isol}		3000	V
$I_{AC-terminal}$		400	A

Characteristics		$T_s = 25\text{ °C}$ unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
V_{CEsat}	$I_C = 900\text{ A}$, $T_j = 25\text{ (125) °C}$; measured at terminal		1,7 (1,9)	2,1	V
V_{CEO}	$T_j = 25\text{ (125) °C}$; at terminal		0,9 (0,8)	1,1 (1)	V
r_{CE}	$T_j = 25\text{ (125) °C}$; at terminal		0,9 (1,3)	1,3 (1,6)	mΩ
I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = V_{CES}$, $T_j = 25\text{ (125) °C}$		3,6 (108)		mA
$E_{on} + E_{off}$	$I_C = 900\text{ A}$, $V_{CC} = 600\text{ V}$		331		mJ
	$T_j = 125\text{ °C}$, $V_{CC} = 900\text{ V}$		585		mJ
R_{CC+EE}	terminal chip, $T_j = 25\text{ °C}$		0,17		mΩ
L_{CE}	top, bottom		4		nH
C_{CHC}	per phase, AC-side		5,1		nF
Inverse diode					
$V_F = V_{EC}$	$I_F = 900\text{ A}$, $T_j = 25\text{ (125) °C}$; measured at terminal		1,5 (1,5)	1,8	V
V_{TO}	$T_j = 25\text{ (125) °C}$		0,9 (0,7)	1,1 (0,9)	V
r_T	$T_j = 25\text{ (125) °C}$		0,7 (0,9)	0,8 (1)	mΩ
E_{rr}	$I_C = 900\text{ A}$, $V_{CC} = 600\text{ V}$		63		mJ
	$T_j = 125\text{ °C}$, $V_{CC} = 900\text{ V}$		84		mJ
Mechanical data					
M_{dc}	DC terminals, SI Units	6		8	Nm
M_{ac}	AC terminals, SI Units	13		15	Nm
w	SKiiP® 3 System w/o heat sink		2,4		kg
w	heat sink		7,5		kg
Thermal characteristics (PX 16 heat sink with fan SKF 16B-230-1); "s" reference to heat sink; "r" reference to built-in temperature sensor (acc. IEC 60747-15)					
$R_{th(j-s)I}$	per IGBT			0,02	K/W
$R_{th(j-s)D}$	per diode			0,038	K/W
Z_{th}	R_i (mK/W) (max. values)	tau _i (s)			
	1 2 3 4	1	2	3	4
$Z_{th(j-r)I}$	3,4 9,6 7 0	363	0,18	0,04	1
$Z_{th(j-r)D}$	12 12 18 20	30	5	0,25	0,04
$Z_{th(r-a)}$	2,1 20 5,5 1,4	210	85	11	0,4

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of

our personal.

SKiiP 1813GB123-3DL



SKiiP® 3

2-pack-integrated intelligent Power System

2-pack
integrated gate driver
SKiiP 1813GB123-3DL

Data

Gate driver features

- CMOS compatible inputs
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protection against under voltage
- Interlock of top/bottom switch
- Isolation by transformers
- Fibre optic interface (option for GB-types only)
- IEC 60068-1 (climate) 40/85/56
- UL recognized file no. 242581

Absolute Maximum Ratings		$T_a = 25\text{ }^\circ\text{C}$ unless otherwise specified	
Symbol	Conditions	Values	Units
V_{S2}	unstabilized 24 V power supply	30	V
V_i	input signal voltage (high)	15 + 0,3	V
dv/dt	secondary to primary side	75	kV/ μ s
V_{isolIO}	input / output (AC, rms, 2)	3000	V
V_{isolPD}	partial discharge extinction voltage, rms, $Q_{PD} \leq 10\text{ pC}$;	1170	V
V_{isol12}	output 1 / output 2 (AC, rms, 2 s)	1500	V
f_{sw}	switching frequency	10	kHz
f_{out}	output frequency for $I_{peak(1)}=I_C$	10	kHz
T_{op} (T_{stg})	operating / storage temperature	- 40 ... + 85	$^\circ\text{C}$

Characteristics		$(T_a = 25\text{ }^\circ\text{C})$			
Symbol	Conditions	min.	typ.	max.	Units
V_{S2}	supply voltage non stabilized	13	24	30	V
I_{S2}	$V_{S2} = 24\text{ V}$	$278+37*f/\text{kHz}+0,00015*(I_{AC}/A)^2$			mA
V_{iT+}	input threshold voltage (High)			12,3	V
V_{iT-}	input threshold voltage (Low)	4,6			V
R_{IN}	input resistance		10		k Ω
C_{IN}	input capacitance		1		nF
$t_{d(on)IO}$	input-output turn-on propagation time		1,3		μ s
$t_{d(off)IO}$	input-output turn-off propagation time		1,3		μ s
$t_{pERRRESET}$	error memory reset time		9		μ s
t_{TD}	top / bottom switch interlock time		3,3		μ s
$I_{analogOUT}$	max. 5mA; 8 V corresponds to 15 V supply voltage for external components		1800		A
I_{s1out}	max. load current			50	mA
I_{TRIPSC}	over current trip level ($I_{analog OUT} = 10\text{ V}$)		2250		A
T_{tp}	over temperature protection	110		120	$^\circ\text{C}$
U_{DCTRIP}	U_{DC} -protection ($U_{analog OUT} = 9\text{ V}$); (option for GB types)		not implemented		V

For electrical and thermal design support please use SEMISEL.
Access to SEMISEL is via SEMIKRON website <http://www.semikron.com>.

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